

# NUP4301MR6T1G, SZNUP4301MR6T1G

## Low Capacitance Diode Array for ESD Protection in Four Data Lines

SZ/NUP4301MR6T1G is a micro-integrated device designed to provide protection for sensitive components from possible harmful electrical transients; for example, ESD (electrostatic discharge).

### Features

- Low Capacitance (1.5 pf Maximum Between I/O Lines)
- Single Package Integration Design
- Provides ESD Protection for JEDEC Standards JESD22  
Machine Model = Class C  
Human Body Model = Class 3B
- Protection for IEC61000-4-2 (Level 4)  
8.0 kV (Contact)  
15 kV (Air)
- Ensures Data Line Speed and Integrity
- Fewer Components and Less Board Space
- Direct the Transient to Either Positive Side or to the Ground
- SZ Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- This is a Pb-Free Device\*

### Applications

- USB 1.1 and 2.0 Data Line Protection
- T1/E1 Secondary IC Protection
- T3/E3 Secondary IC Protection
- HDSL, IDSL Secondary IC Protection
- Video Line Protection
- Microcontroller Input Protection
- Base Stations
- I<sup>2</sup>C Bus Protection



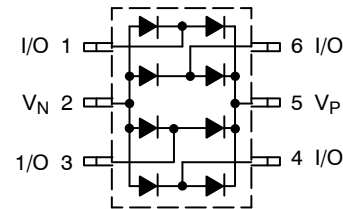
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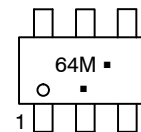


SC-74  
CASE 318F  
PLASTIC

### PIN CONFIGURATION AND SCHEMATIC



### MARKING DIAGRAM



64 = Device Code  
M = Date Code\*  
▪ = Pb-Free Package

(Note: Microdot may be in either location.)

\*Date Code orientation may vary depending upon manufacturing location.

### ORDERING INFORMATION

Device	Package	Shipping†
NUP4301MR6T1G	SC-74 (Pb-Free)	3,000 / Tape & Reel
SZNUP4301MR6T1G	SC-74 (Pb-Free)	3,000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# NUP4301MR6T1G, SZNUP4301MR6T1G

## MAXIMUM RATINGS (Each Diode) ( $T_J = 25^\circ\text{C}$ unless otherwise noted)

Rating	Symbol	Value	Unit
Reverse Voltage	$V_R$	70	Vdc
Forward Current	$I_F$	200	mAdc
Peak Forward Surge Current	$I_{FM(surge)}$	500	mAdc
Repetitive Peak Reverse Voltage	$V_{RRM}$	70	V
Average Rectified Forward Current (Note 1) (averaged over any 20 ms period)	$I_{F(AV)}$	715	mA
Repetitive Peak Forward Current	$I_{FRM}$	450	mA
Non-Repetitive Peak Forward Current t = 1.0 $\mu\text{s}$ t = 1.0 ms t = 1.0 S	$I_{FSM}$	2.0 1.0 0.5	A

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR-5 =  $1.0 \times 0.75 \times 0.062$  in.

## THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	$^\circ\text{C/W}$
Lead Solder Temperature, Maximum 10 Seconds Duration	$T_L$	260	$^\circ\text{C}$
Junction Temperature	$T_J$	-40 to +85	$^\circ\text{C}$
Storage Temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

## ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ unless otherwise noted) (Each Diode)

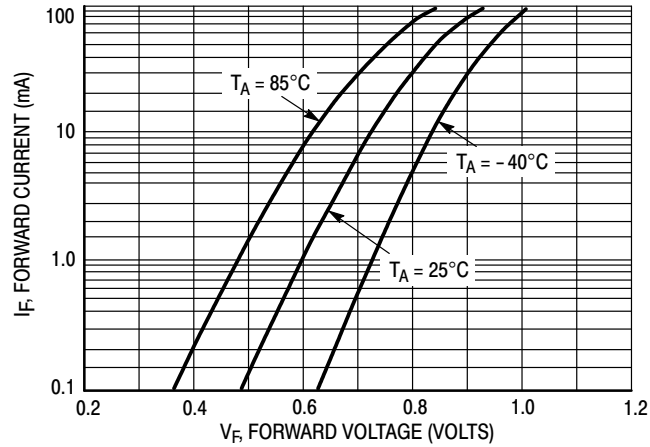
Characteristic	Symbol	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>					
Reverse Breakdown Voltage ( $I_{(BR)} = 100 \mu\text{A}$ )	$V_{(BR)}$	70	-	-	Vdc
Reverse Voltage Leakage Current ( $V_R = 70$ Vdc) ( $V_R = 25$ Vdc, $T_J = 150^\circ\text{C}$ ) ( $V_R = 70$ Vdc, $T_J = 150^\circ\text{C}$ )	$I_R$	-	-	2.5 30 50	$\mu\text{Adc}$
Capacitance (between I/O pins) ( $V_R = 0$ V, $f = 1.0$ MHz)	$C_D$	-	0.8	1.5	pF
Capacitance (between I/O pin and ground) ( $V_R = 0$ V, $f = 1.0$ MHz)	$C_D$	-	1.6	3	pF
Forward Voltage ( $I_F = 1.0$ mAdc) ( $I_F = 10$ mAdc) ( $I_F = 50$ mAdc) ( $I_F = 150$ mAdc)	$V_F$	-	-	715 855 1000 1250	mVdc

2. Alumina =  $0.4 \times 0.3 \times 0.024$  in. 99.5% alumina.

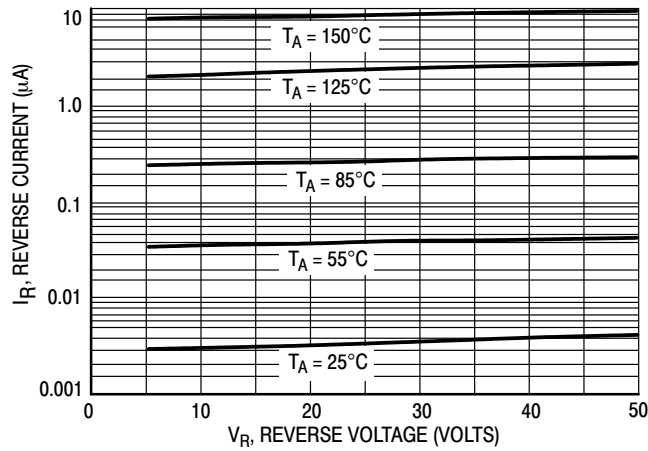
3. Include SZ-prefix devices where applicable.

# NUP4301MR6T1G, SZNUP4301MR6T1G

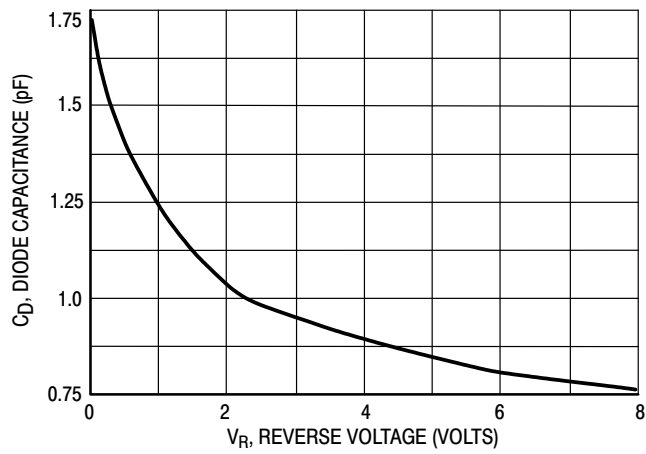
## Curves Applicable to Each Cathode



**Figure 1. Forward Voltage**



**Figure 2. Leakage Current**

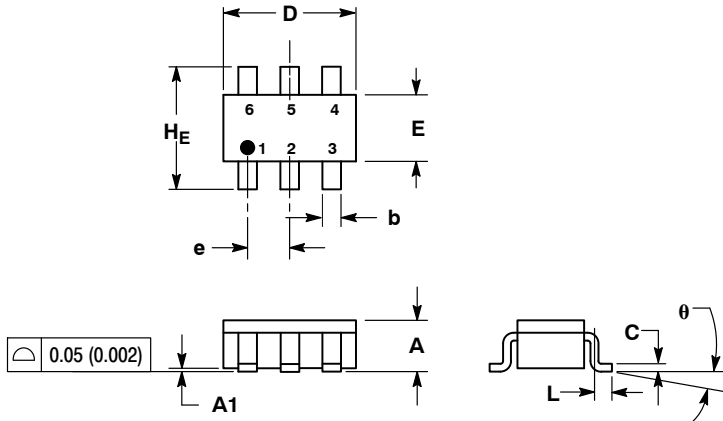


**Figure 3. Capacitance**

# NUP4301MR6T1G, SZNUP4301MR6T1G

## PACKAGE DIMENSIONS

SC-74  
CASE 318F-05  
ISSUE M

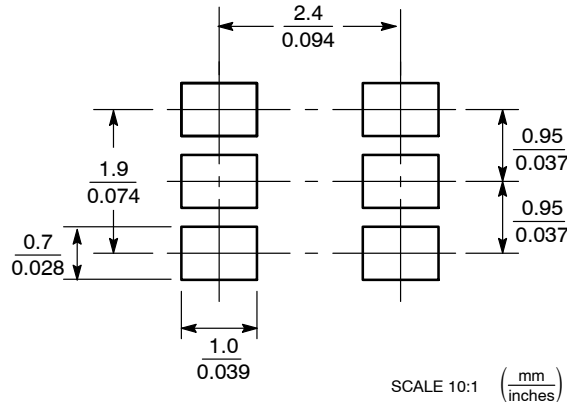


### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. 318F-01, -02, -03, -04 OBSOLETE. NEW STANDARD 318F-05.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.90	1.00	1.10	0.035	0.039	0.043
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.25	0.37	0.50	0.010	0.015	0.020
c	0.10	0.18	0.26	0.004	0.007	0.010
D	2.90	3.00	3.10	0.114	0.118	0.122
E	1.30	1.50	1.70	0.051	0.059	0.067
e	0.85	0.95	1.05	0.034	0.037	0.041
L	0.20	0.40	0.60	0.008	0.016	0.024
HE	2.50	2.75	3.00	0.099	0.108	0.118
θ	0°	-	10°	0°	-	10°

### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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